

High Output Current, Single Supply, Rail-to-Rail Output Dual CMOS Operational Amplifier

□ GENERAL DESCRIPTION

The NJU7036 is a Rail-to-Rail Output operational amplifier of single power supply operation. It has the characteristic of high power output current and is suitable for driving heavy loads such as a small motor, LED, and speakers. It has up to 0.15 V saturation voltages at an output current of 250mA.

Therefore it can reduce the electric power loss in IC and contribute to the design of low power consumption. Moreover, micro leadless package (PCSP20-E3) is available for it, so that it can also contribute to the miniaturization of the equipment.

□ FEATURES

- Rail-to-Rail Output $V_o=4.7V_{pp}$ min. at $VDD=5V, I_o=250mA$
- Single Supply
- Operating Voltage $Vopr=2.7V$ to $5.5V$
- Package Outline PCSP20-E3
- CMOS Process
- Thermal Shutdown Circuit
- Current Limit Circuit

□ PACKAGE OUTLINE



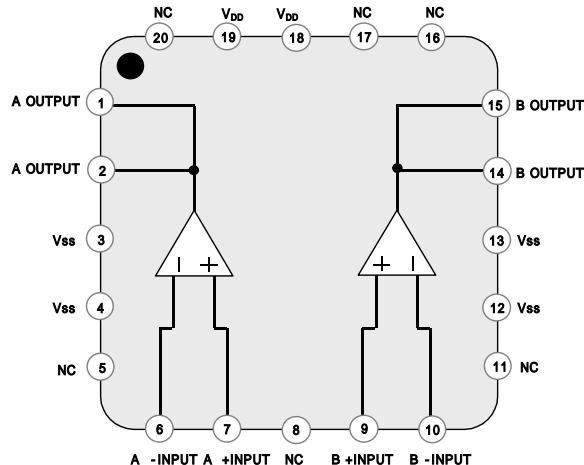
**NJU7036SE3
(PCSP20-E3)**

□ APPLICATION

- Motor Drivers , Audio Amplifiers , LED Drivers , etc.

□ PIN CONFIGURATION (Top View)

NJU7036SE3



1,2	A OUTPUT	10	B -INPUT
3,4	V_{SS}	11	NC
5	NC	12,13	V_{SS}
6	A -INPUT	14,15	B OUTPUT
7	A +INPUT	16,17	NC
8	NC	18,19	V_{DD}
9	B +INPUT	20	NC

VDD terminal, VSS terminal and OUTPUT terminal use two or more pins respectively and are lowering terminal resistance.

You shall connect each two pins (VDD, VSS and OUTPUT) with the same electric potential.

When only one pin is used, the internal terminal resistance becomes high and the maximum output voltage declines.

NJU7036

□ ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNIT
Supply Voltage	V _{DD}	7.0	V
Power Dissipation	P _D	PCSP20(The back pad is mounted.) : 560 *1), 980 *2) (The back pad is not mounted.): 550 *1), 850 *2)	mW
Output Peak Current	I _{OP}	500	mA
Input Common Mode Voltage	V _{ICM}	-0.3 to 7.0 *3)	V
Differential Input Voltage	V _{ID}	±7 *3)	V
Operating Temperature Range	T _{opr}	-40 to +85	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

*1) EIA/JEDEC STANDARD Test board (76.2 x 114.3 x 1.6mm, 4layers, FR-4) mounting

*2) EIA/JEDEC STANDARD Test board (76.2 x 114.3 x 1.6mm, 2layers, FR-4) mounting

*3) If the supply voltage V_{DD} is less than 7V, the input voltage must not over the V_{DD} level through 7V is limit specified.

□ RECOMMENDED OPERATING CONDITION

Ta=25°C

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V _{DD}	2.7 to 5.5	V

□ ELECTRICAL CHARACTERISTICS

V_{DD}=5V, V_{SS}=0V, V_{IC}=2.5V, RL=8Ω(connected

V_{DD}

/2), Ta=25°C

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
DC CHARACTERISTICS						
Maximum Output Voltage *RL=OPEN	V _{OH1} V _{OH2} V _{OH3} V _{OL1} V _{OL2} V _{OL3}	I _{source} =250mA I _{source} =150mA I _{source} =50mA I _{sink} =250mA I _{sink} =150mA I _{sink} =50mA	4.85 4.88 4.92 -	4.90 4.94 4.98 0.10 0.06 0.02	- - - 0.15 0.12 0.08	V V V V V V
Input Offset Voltage	V _{io}		-	2	10	mV
Input Bias Current	I _B		-	1	-	pA
Input Offset Current	I _{IO}		-	1	-	pA
Large Signal Voltage Gain	A _V	V _O = V _{DD} /2±2V	80	100	-	dB
Common Mode Rejection Ratio	CMR	V _{ICM} =0V to 3.8V	60	80	-	dB
Supply Voltage Rejection Ratio	SVR	V _{DD} =2.7V to 5.5V	60	80	-	dB
Input Common Mode Voltage Range	V _{ICM}	CMR≥60dB	0	-	3.8	V
Operating Current	I _{DD}	No Signal, RL=open	-	3.5	5.3	mA
AC CHARACTERISTICS						
Unity Gain Bandwidth	f _T	G _V =6dB, C _L =10pF	-	0.4	-	MHz
Equivalent Input Noise Voltage	V _{NI}	f=1kHz, G _V =6dB, Rs=100Ω,	-	60	-	nV/√Hz
Total Harmonic Distortion (THD+N)	THD	G _V =6dB, C _L =10pF fin=1kHz, Po=250mW	-	0.03	-	%
Output Power	Po	G _V =6dB, C _L =10pF fin=1kHz, THD≤5%	-	400	-	mW

Channel Separation	CS	f=1kHz	-	90	-	dB
PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
TRANSIENT CHARACTERISTICS Slew Rate	SR	G _V =0dB, C _L =10pF Vin=1.0Vpp	-	0.7	-	V/μs
$V_{DD}=3V, V_{SS}=0V, V_{IC}=1.5V, RL=8\Omega$ (connected $V_{DD}/2$), Ta=25°C						
PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
DC CHARACTERISTICS						
Maximum Output Voltage *RL=OPEN	V _{OH1} V _{OH2} V _{OH3} V _{OL1} V _{OL2} V _{OL3}	I _{source} =250mA I _{source} =150mA I _{source} =50mA I _{sink} =250mA I _{sink} =150mA I _{sink} =50mA	2.77 2.83 2.90 -	2.85 2.91 2.97 0.15 0.09 0.03	- - - 0.23 0.17 0.10	V
Input Offset Voltage	V _{io}		-	2	10	mV
Input Bias Current	I _B		-	1	-	pA
Input Offset Current	I _{IO}		-	1	-	pA
Large Signal Voltage Gain	A _V	V _O = V _{DD} /2±1V	70	90	-	dB
Common Mode Rejection Ratio	CMR	V _{ICM} =0V to 1.8V	60	80	-	dB
Supply Voltage Rejection Ratio	SVR	V _{DD} =2.7V to 3.5V	58	70	-	dB
Input Common Mode Voltage Range	V _{ICM}	CMR≥60dB	0	-	1.8	V
Operating Current	I _{DD}	No Signal, RL=open	-	2.4	3.5	mA
AC CHARACTERISTICS						
Unity Gain Bandwidth	f _T	G _V =6dB, C _L =10pF	-	0.4	-	MHz
Equivalent Input Noise Voltage	V _{NI}	f=1kHz, G _V =6dB, R _S =100Ω,	-	60	-	nV/√Hz
Total Harmonic Distortion (THD+N)	THD	G _V =6dB, C _L =10pF f _{in} =1kHz, P _O =60mW	-	0.06	-	%
Output Power	P _O	G _V =6dB, C _L =10pF f _{in} =1kHz, THD≤5%	-	150	-	mW
Channel Separation	CS	f=1kHz	-	90	-	dB
TRANSIENT CHARACTERISTICS						
Slew Rate	SR	G _V =0dB, C _L =10pF Vin=0.5Vpp	-	0.5	-	V/μs

□Application Notes

•Package Power, Power Dissipation and Output Power

IC is heated by own operation and possibly gets damage when the junction power exceeds the acceptable value called Power Dissipation P_D . The dependence of the NJU7036 P_D on ambient temperature is shown in Fig 1. The plots are depended on following two points. The first is P_D on ambient temperature 25°C, which is the maximum power dissipation. The second is 0W, which means that the IC cannot radiate any more. Conforming the maximum junction temperature T_{jmax} to the storage temperature T_{stg} derives this point. Fig.1 is drawn by connecting those points and conforming the P_D lower than 25mW to it on 25°C. The P_D is shown following formula as a function of the ambient temperature between those points.

$$\text{Dissipation Power } P_D = \frac{T_{jmax} - T_a}{\theta_{ja}} \text{ [W]} \quad (\text{Ta}=25^\circ\text{C} \sim \text{Ta}=150^\circ\text{C})$$

Where, θ_{ja} is heat thermal resistance which depends on parameters such as package material, frame material and so on. Therefore, P_D is different in each package.

While, the actual measurement of dissipation power on NJU7036 is obtained using following equation.

$$(\text{Actual Dissipation Power}) = (\text{Supply Voltage } V_{DD}) \times (\text{Supply Current } I_{DD}) - (\text{Output Power } P_o)$$

The NJU7036 should be operated in lower than P_D of the actual dissipation power.

To sustain the steady state operation, take account of the Dissipation Power and thermal design.

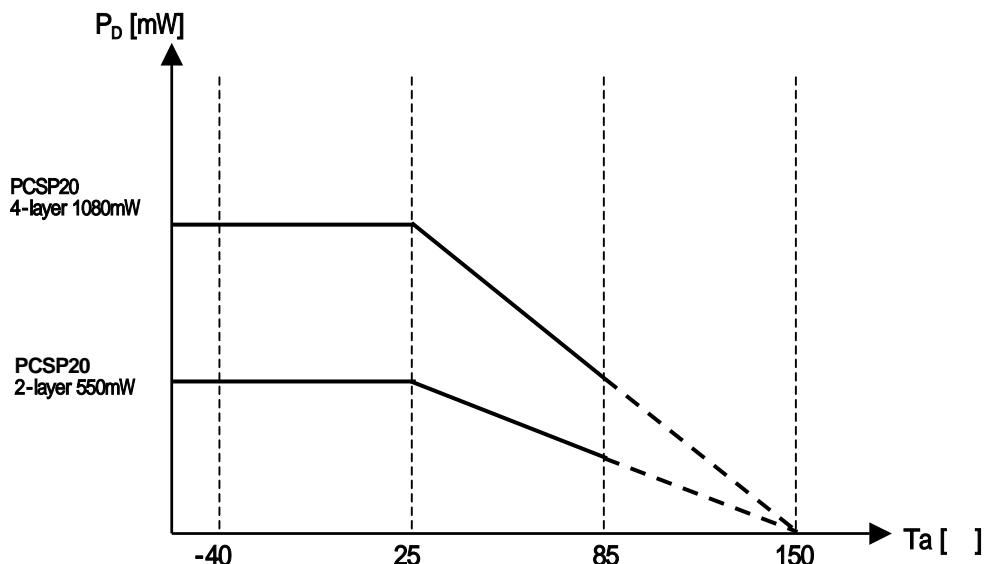


Fig.1 Power Dissipations vs. Ambient Temperature on the NJU7036.

•Thermal Protection

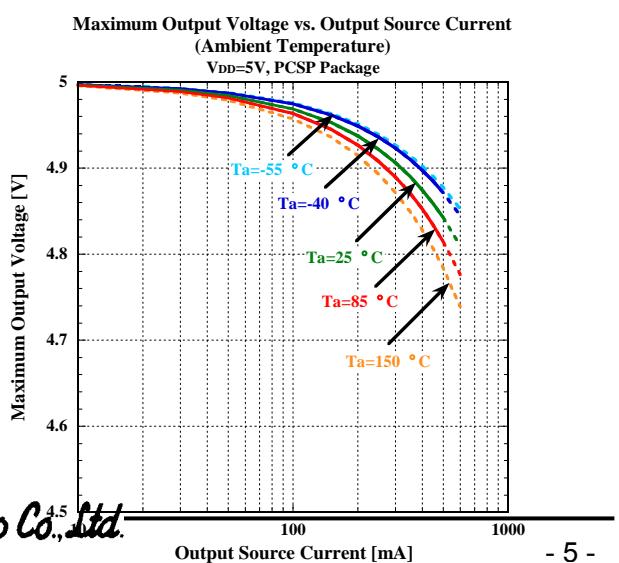
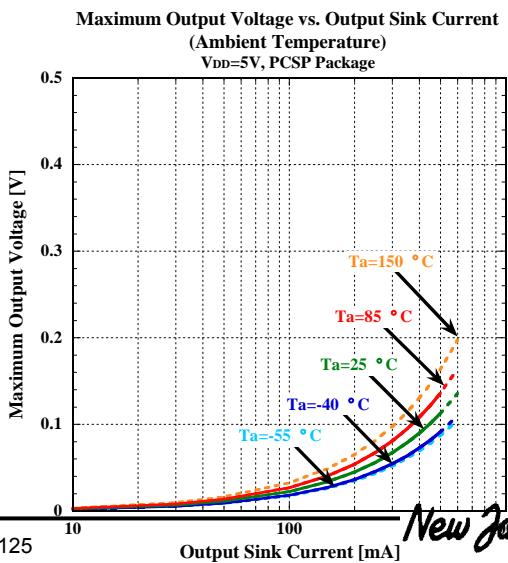
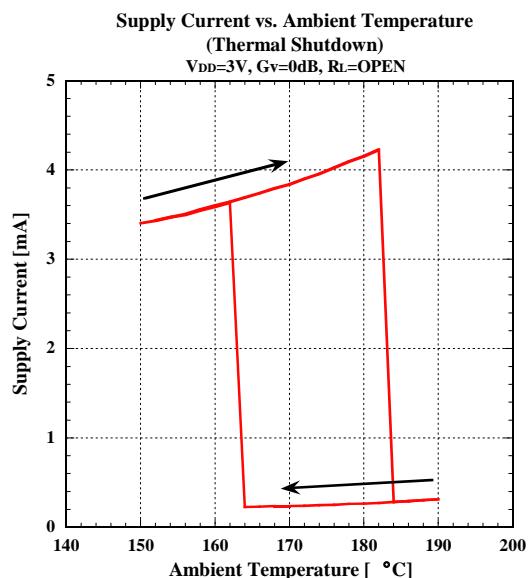
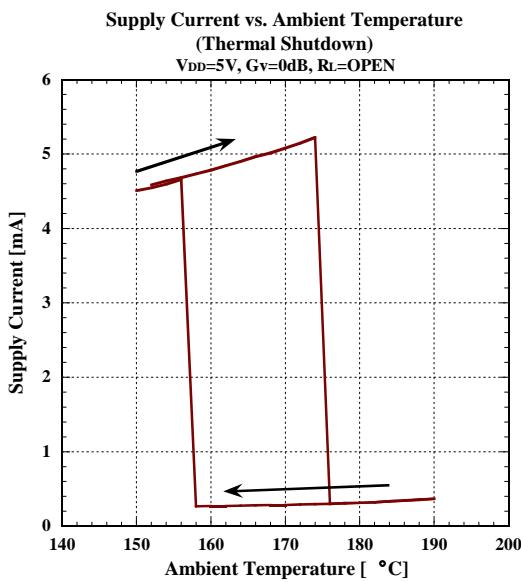
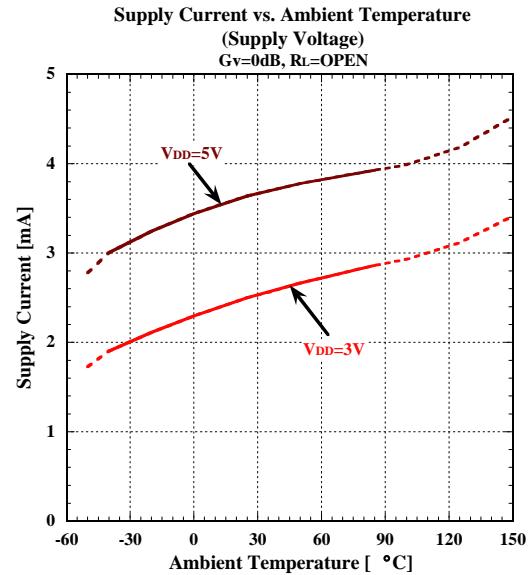
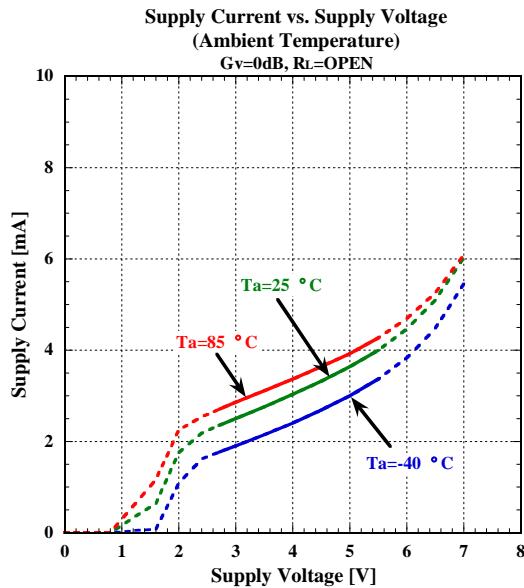
The NJU7036 is designed with Thermal Shut Down (TSD) circuitry that protects itself from damage caused by overload condition. The TSD circuitry is operated when the junction temperature reaches approximately 180°C, and the actual measurement of dissipation power is reduced by the stopped output current. When the junction temperature cools to approximately 150°C, the output circuitry is automatically re-enabled. Continuously running the NJU7036 into the thermal shutdown possibly damages device since the TSD circuit doesn't have active cooling function such as heat sinking. To sustain the steady state operation, the NJU7036 should be operated in lower than the Dissipation Power of the actual dissipation power.

•Current Limit

The NJU7036 should be operated in lower than 500mA of output current. The NJU7036 has current limiting circuitry that prevents from exceeding output current caused by grounding in order to enhance the safety of operation. The circuitry limits output current to approximately 1A. Although the output current is lower than 500mA, the device possibly

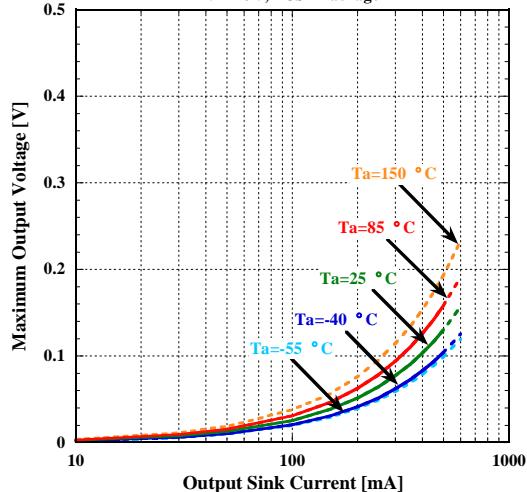
gets damage due to heating by output current. To sustain the steady state operation, the NJU7036 should be operated in lower than 500mA of output current and lower than the Dissipation Power of the actual dissipation power.

□ TYPICAL CHARACTERISTICS

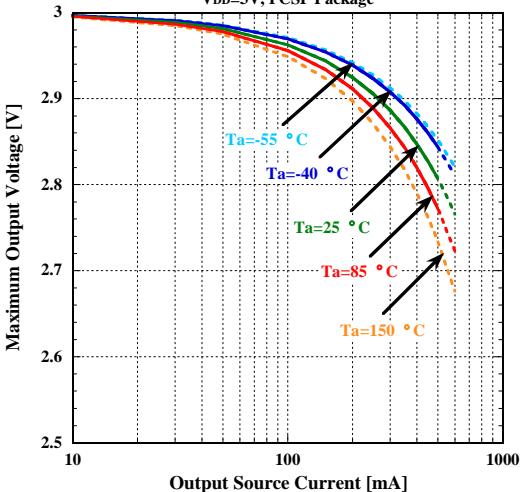


□ TYPICAL CHARACTERISTICS

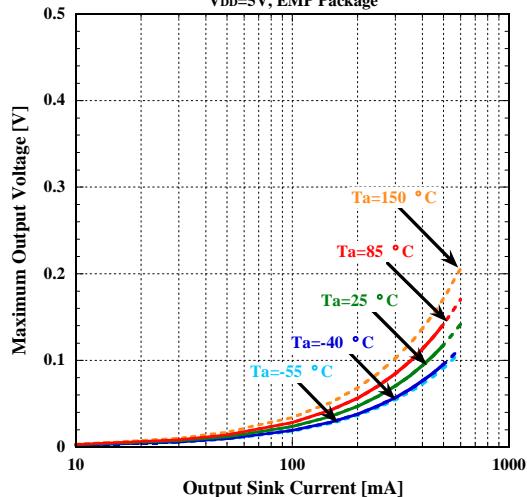
**Maximum Output Voltage vs. Output Sink Current
(Ambient Temperature)**
VDD=3V, PCSP Package



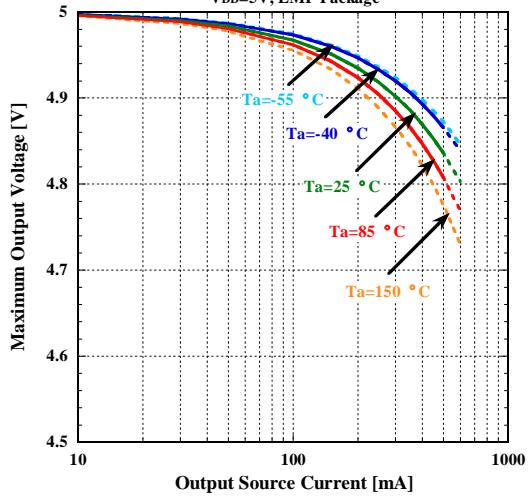
**Maximum Output Voltage vs. Output Source Current
(Ambient Temperature)**
VDD=3V, PCSP Package



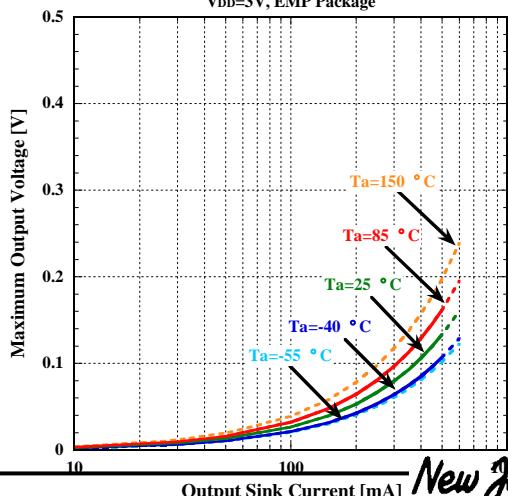
**Maximum Output Voltage vs. Output Sink Current
(Ambient Temperature)**
VDD=5V, EMP Package



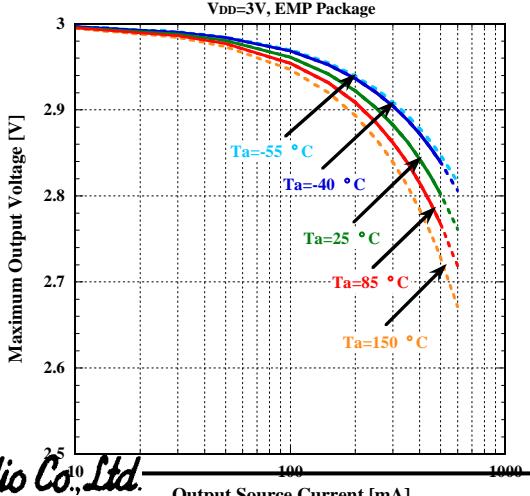
**Maximum Output Voltage vs. Output Source Current
(Ambient Temperature)**
VDD=5V, EMP Package



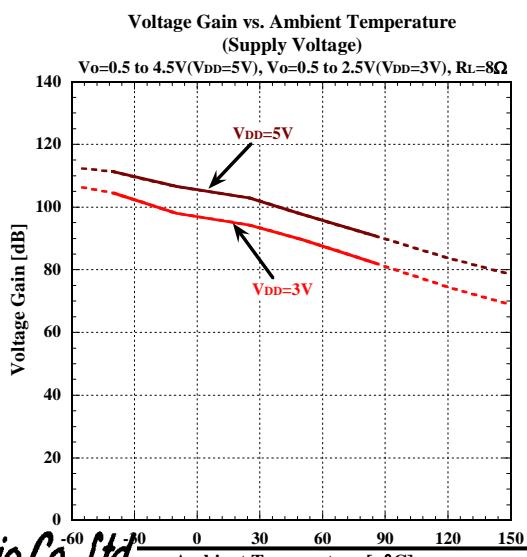
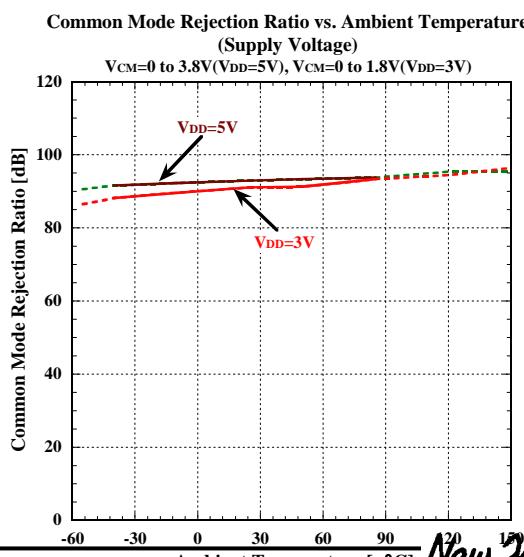
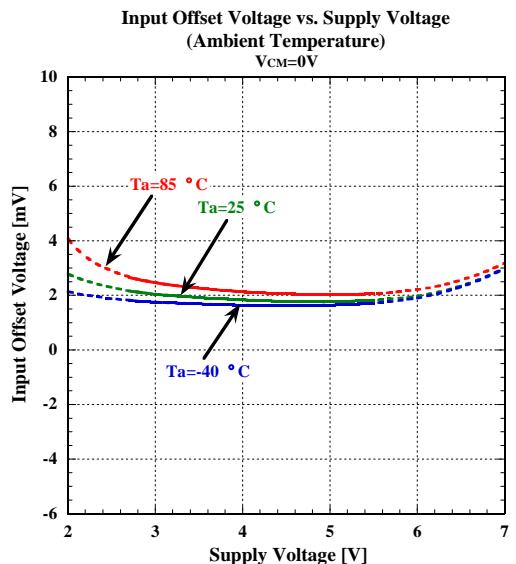
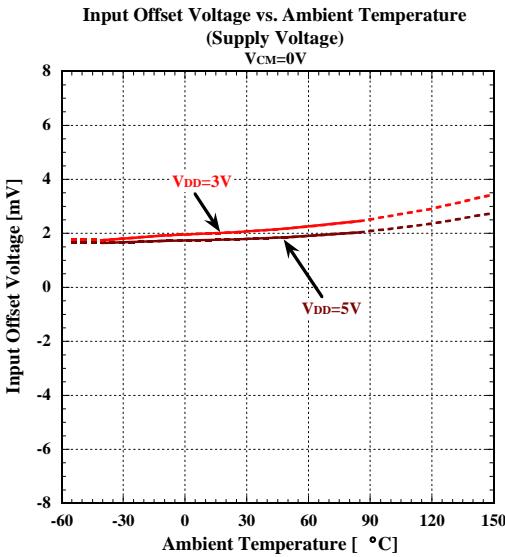
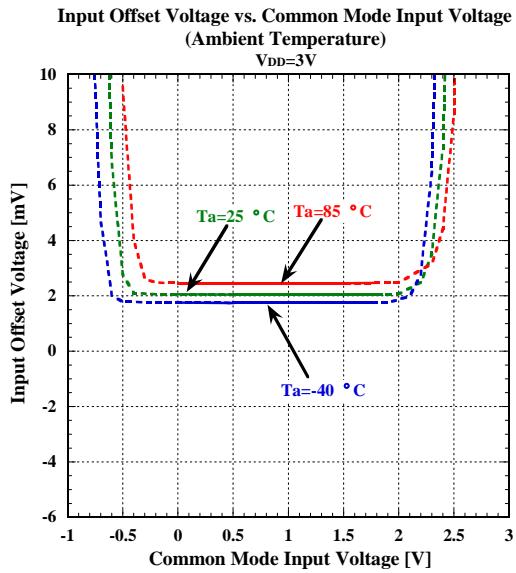
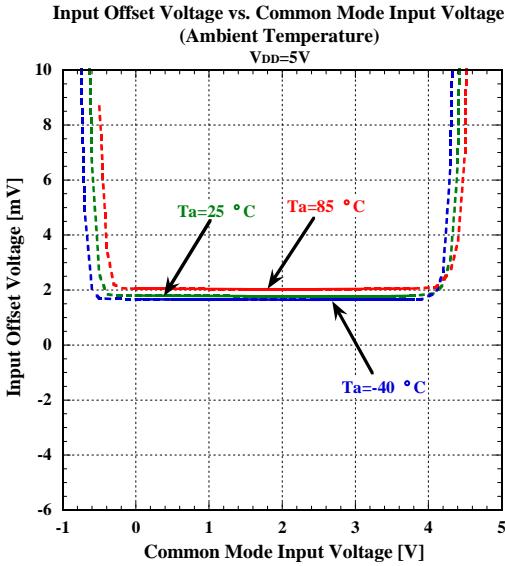
**Maximum Output Voltage vs. Output Sink Current
(Ambient Temperature)**
VDD=3V, EMP Package



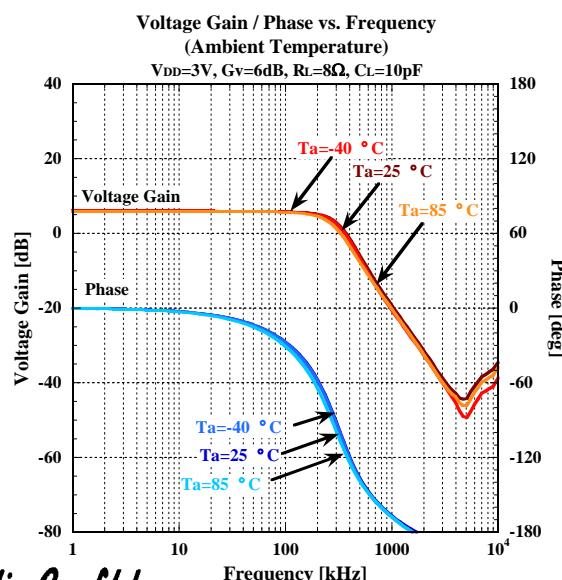
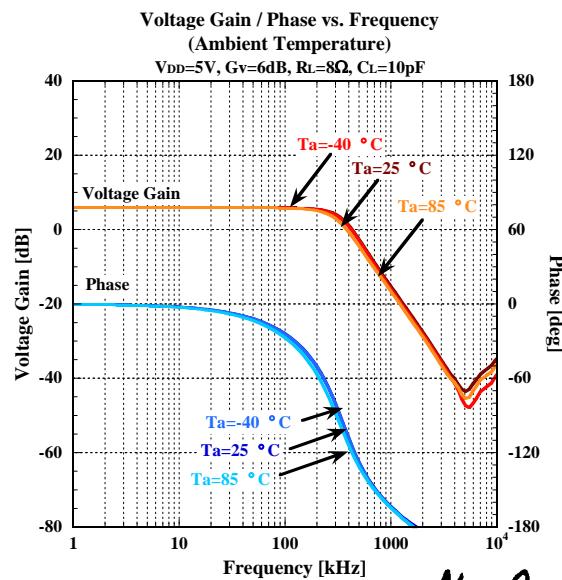
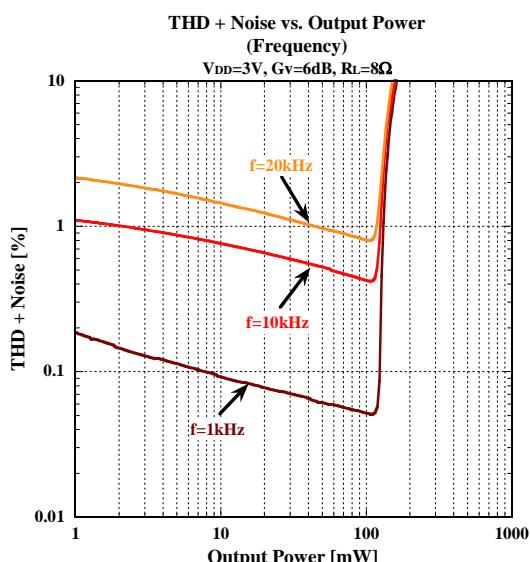
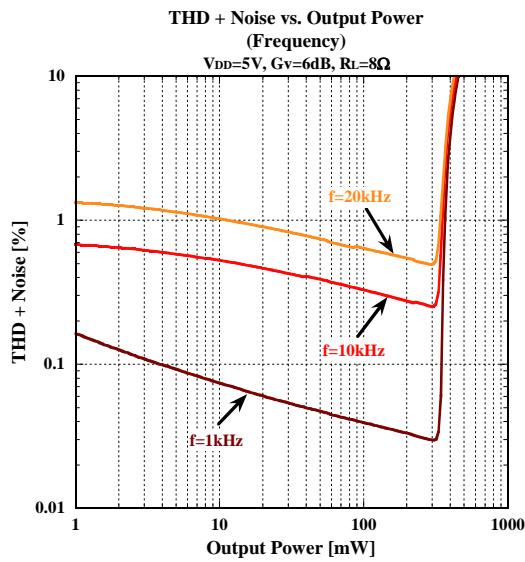
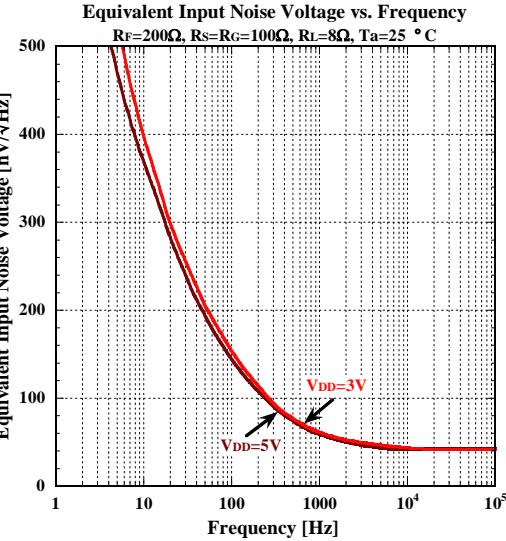
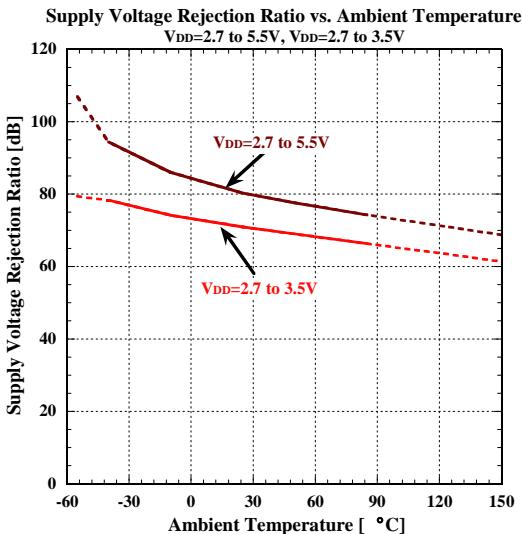
**Maximum Output Voltage vs. Output Source Current
(Ambient Temperature)**
VDD=3V, EMP Package



□ TYPICAL CHARACTERISTICS



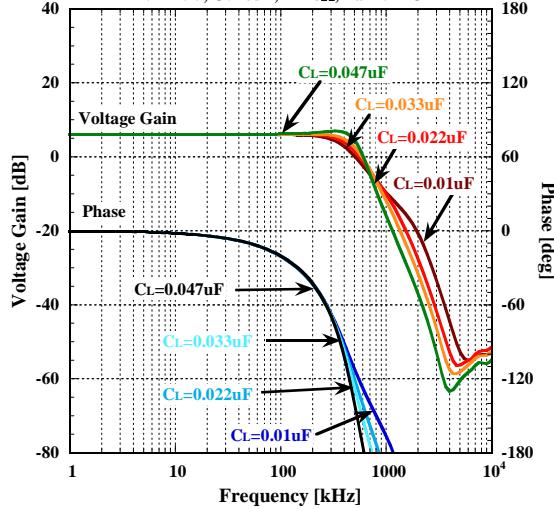
□ TYPICAL CHARACTERISTICS



□ TYPICAL CHARACTERISTICS

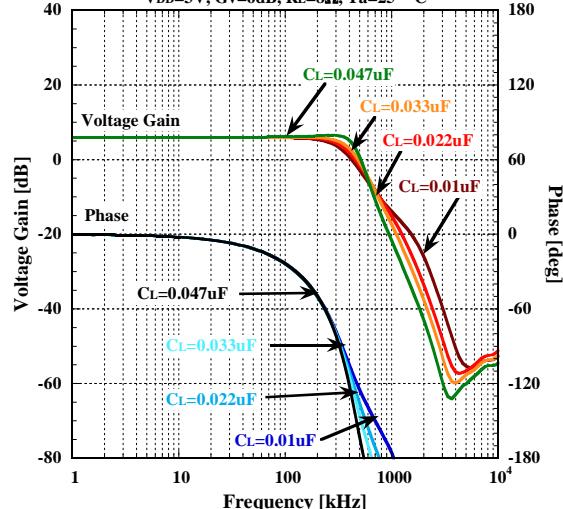
Voltage Gain / Phase vs. Frequency
(Load Capacitance)

VDD=5V, Gv=6dB, RL=8Ω, Ta=25 °C



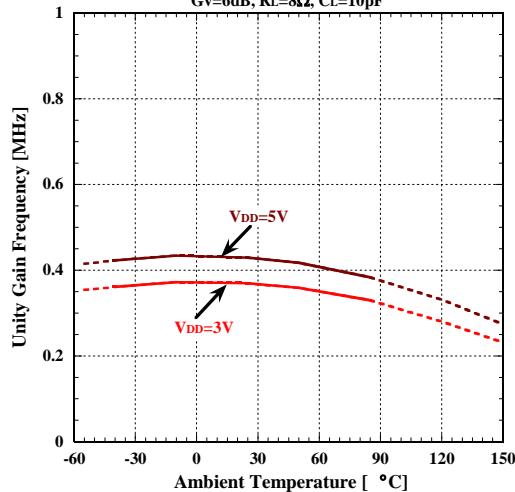
Voltage Gain / Phase vs. Frequency
(Load Capacitance)

VDD=3V, Gv=6dB, RL=8Ω, Ta=25 °C



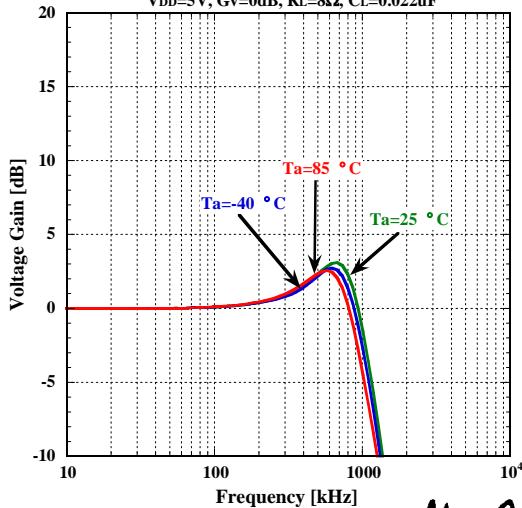
Unity Gain Frequency vs. Ambient Temperature
(Supply Voltage)

Gv=6dB, RL=8Ω, CL=10pF



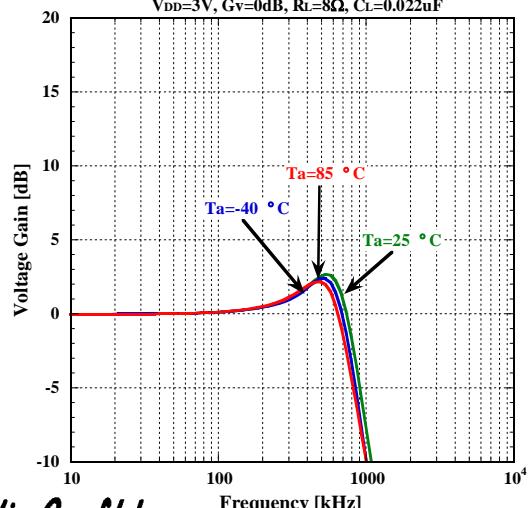
Voltage Follower Peak
(Ambient temperature)

VDD=5V, Gv=0dB, RL=8Ω, CL=0.022μF

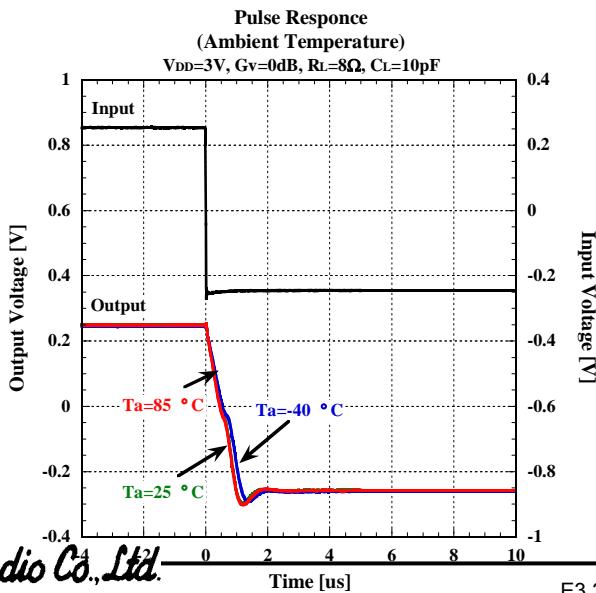
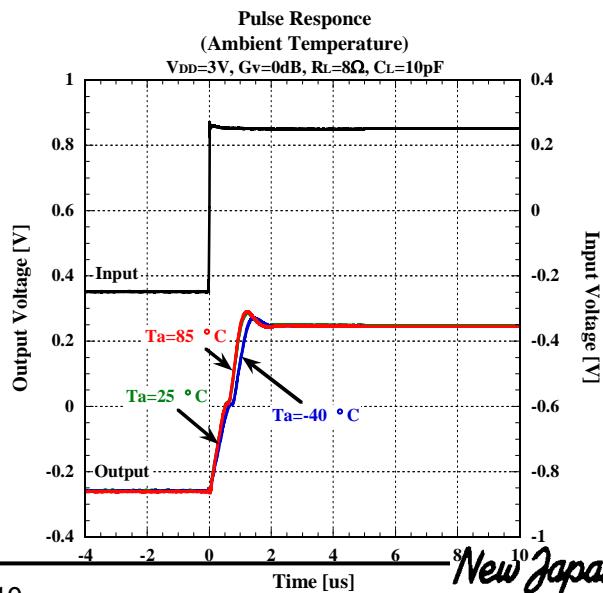
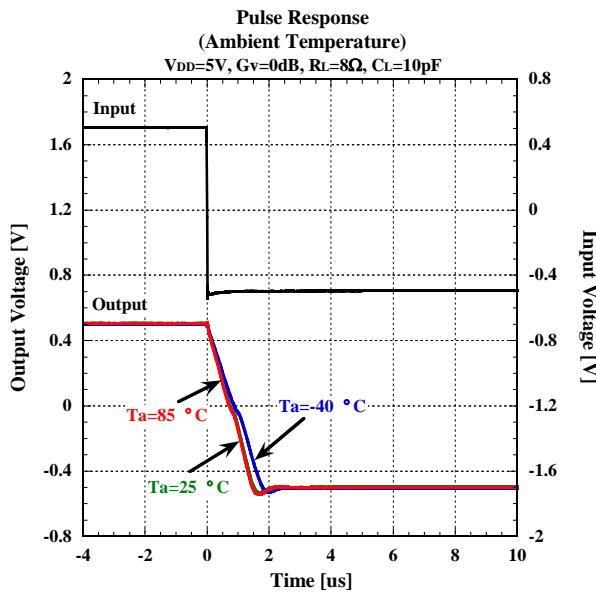
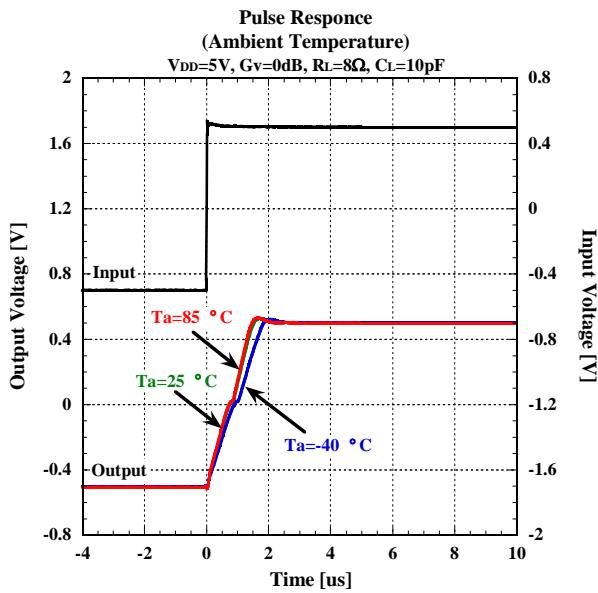
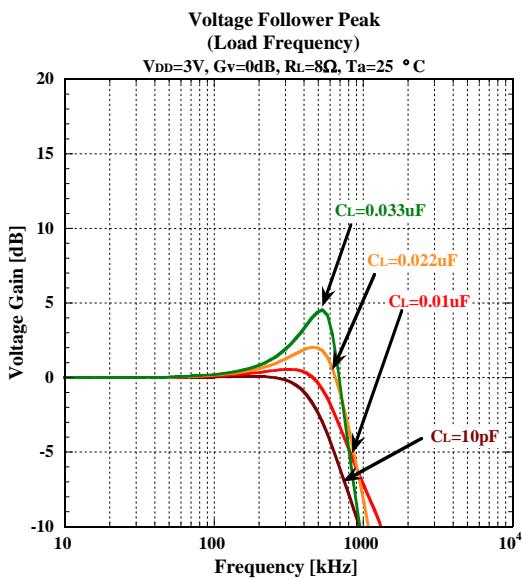
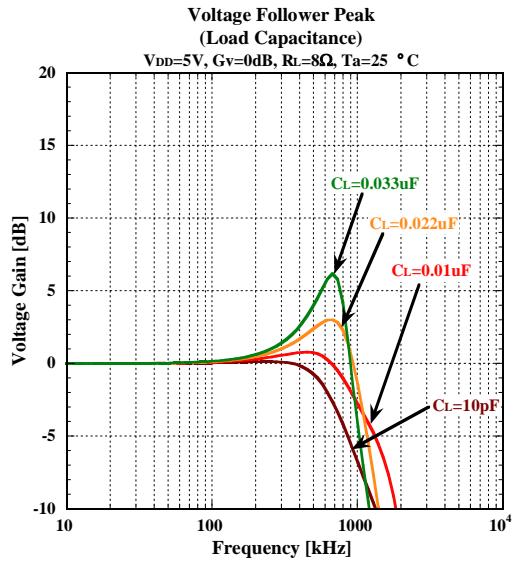


Voltage Follower Peak
(Ambient Temperature)

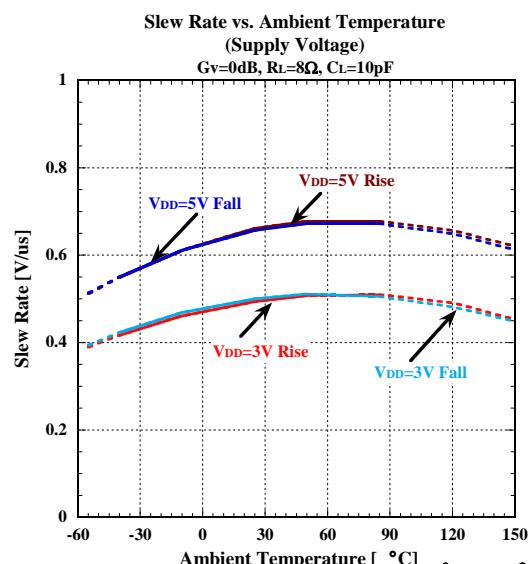
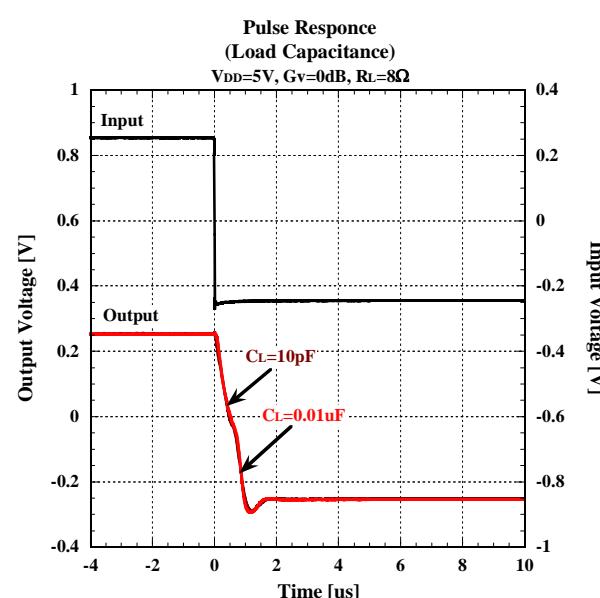
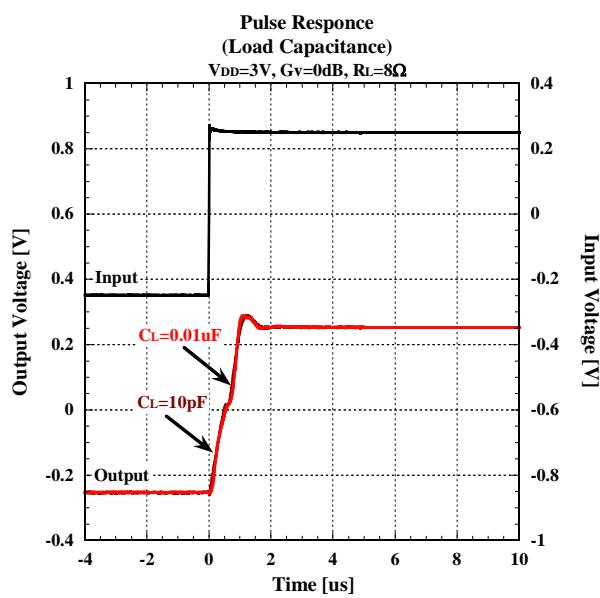
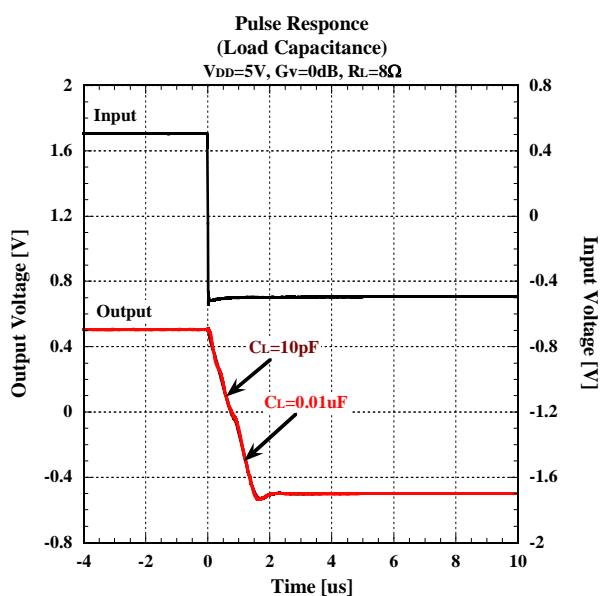
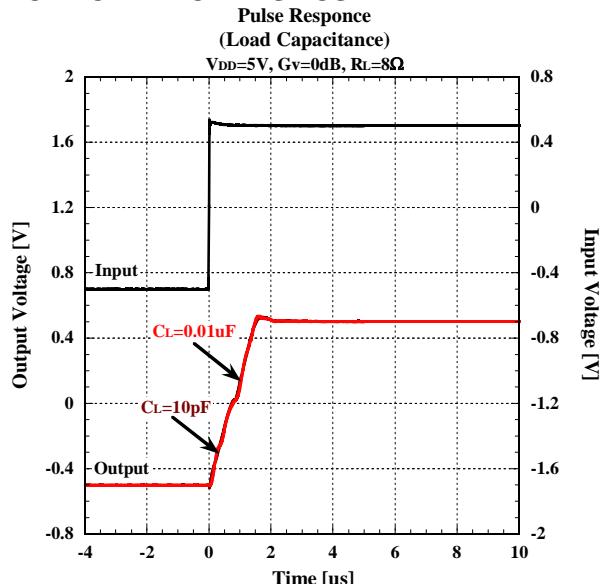
VDD=3V, Gv=0dB, RL=8Ω, CL=0.022μF



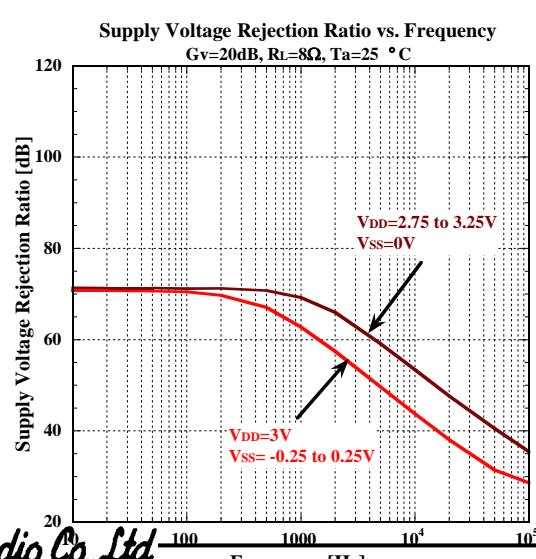
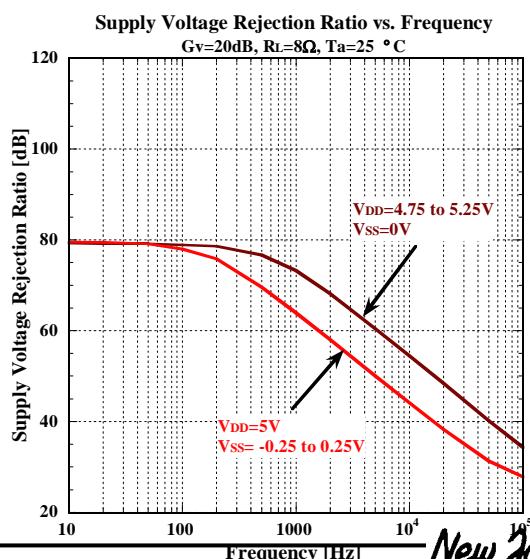
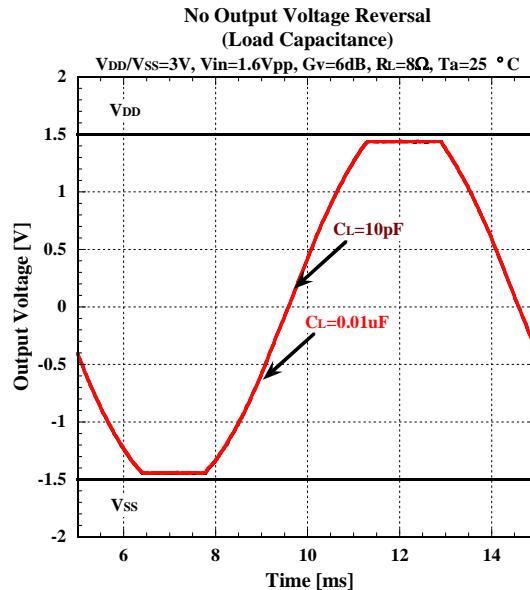
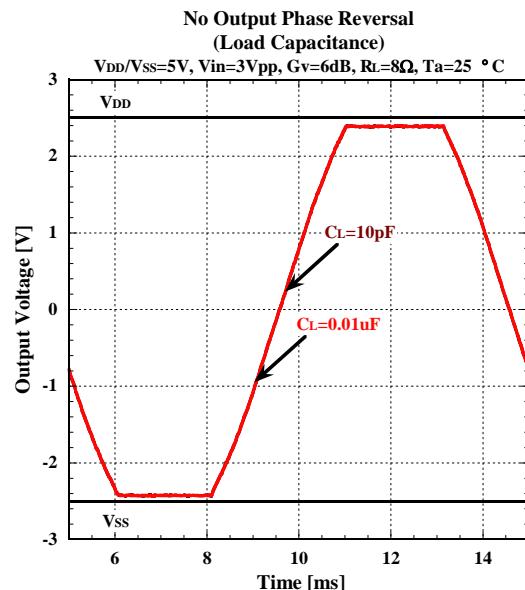
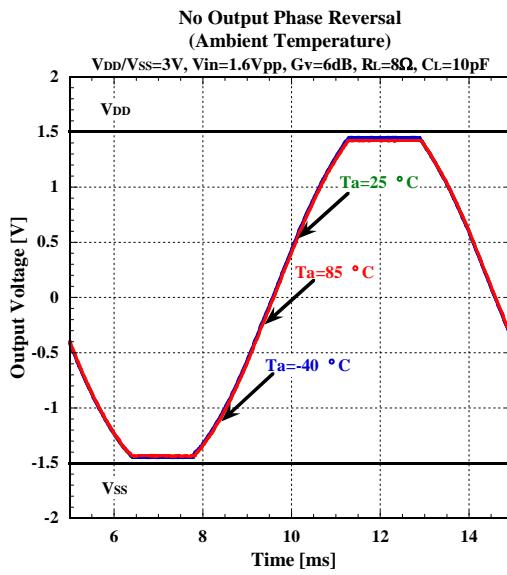
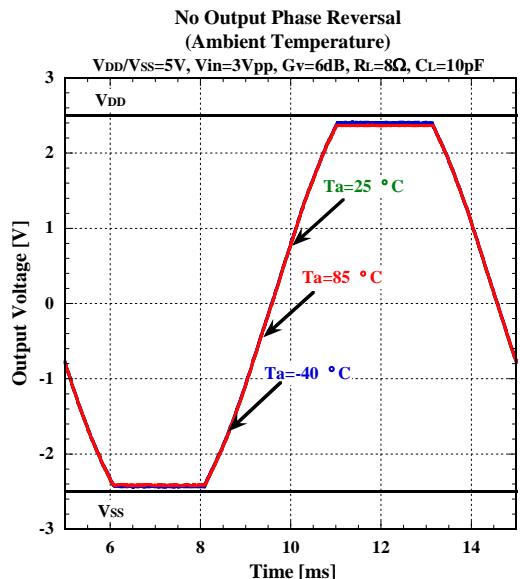
□ TYPICAL CHARACTERISTICS



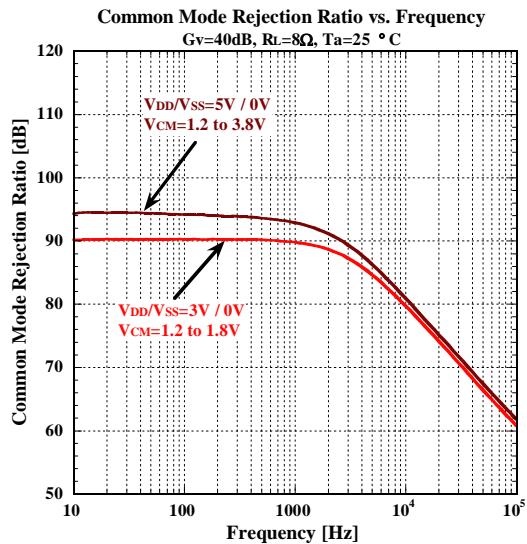
□ TYPICAL CHARACTERISTICS



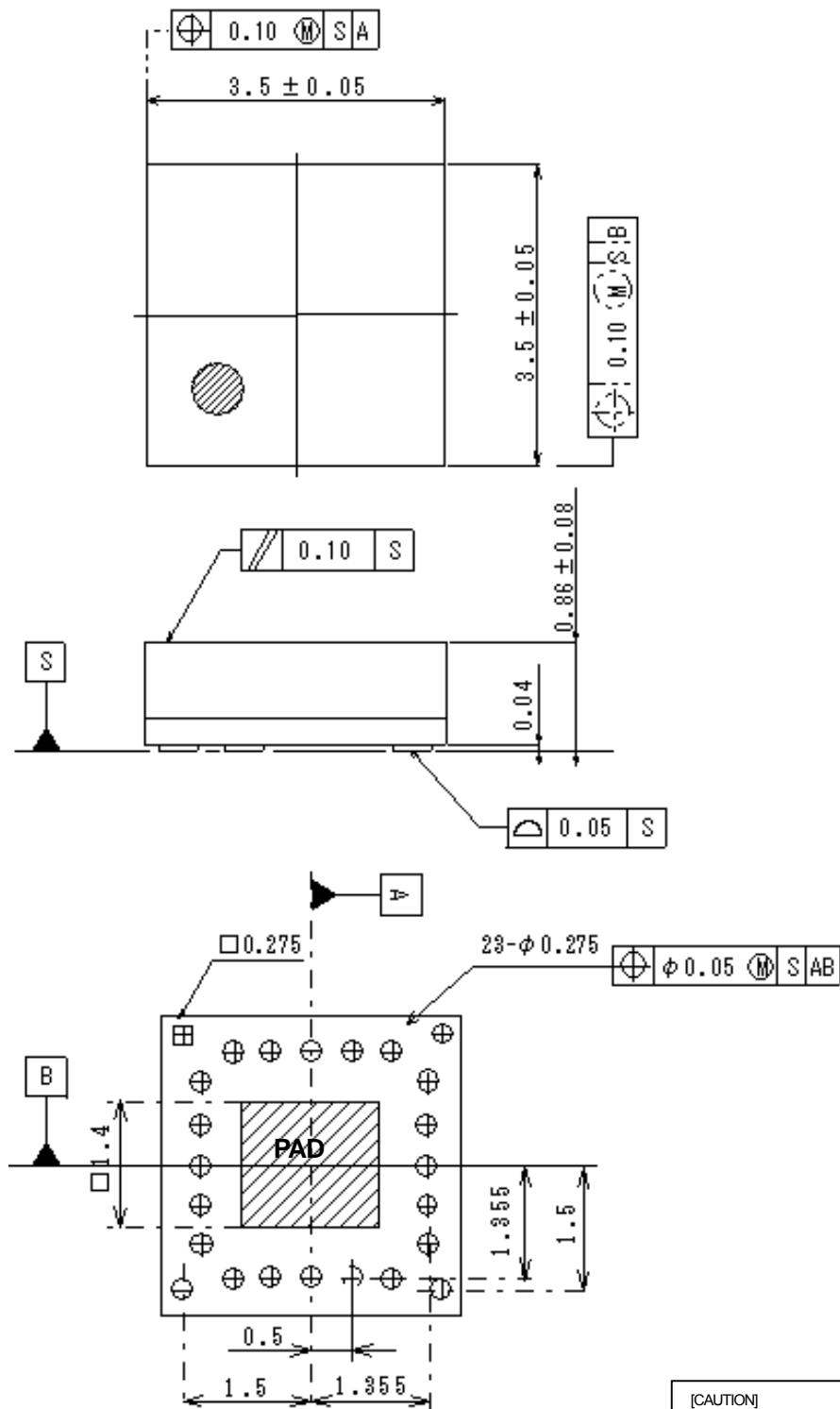
□ TYPICAL CHARACTERISTICS



□ TYPICAL CHARACTERISTICS



□ PACKAGE DIMENSIONS

PCSP-20E3

The PAD is electrically not connected to the backside of the die.
Moreover, Please mount PAD on plain GND to give heat radiation.

[CAUTION]
The specifications on this databook are only given for information, without any guarantee as regards either mistakes or omissions. The application circuits in this databook are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial rights.